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AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

- 1. (issued) A surface acoustic wave device comprising:
- a LiTaO₃ substrate; and

an interdigital transducer provided on the LiTaO₃ substrate, said interdigital transducer containing as a major component at least one of Au, Ag, Ta, Mo, Cu, Ni, Cr, Zn, and W; wherein

said interdigital transducer has a normalized film thickness H/ λ within a range of approximately 0.001 to approximately 0.05 so as to excite a shear horizontal wave.

- 2. (issued) A surface acoustic wave device according to claim 1, wherein said interdigital transducer includes Au as a major component, said substrate has Euler angles of approximately (0°, 125° 146°, 0°± 5°).
- 3. (issued) A surface acoustic wave device according to claim 1, wherein said interdigital transducer includes Ag as a major component, said substrate has Euler angles of approximately (0°, 125° 140°, 0° \pm 5°), and said normalized film thickness H/ λ is within the range of approximately 0.002 to 0.05.
- 4. (issued) A surface acoustic wave device according to claim 1, wherein said interdigital transducer includes Ta as a major component, said substrate has Euler angles of approximately (0°, 125° 140°, 0° \pm 5°), and said normalized film thickness H/ λ is within the range of approximately 0.002 to 0.05.

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- 5. (issued) A surface acoustic wave device according to claim 1, wherein said interdigital transducer includes Mo as a major component, said substrate has Euler angles of approximately (0°, 125° 134°, 0° \pm 5°), and said normalized film thickness H/ λ is within the range of approximately 0.005 to 0.05.
- 6. (issued) A surface acoustic wave device according to claim 1, wherein said interdigital transducer includes Cu as a major component, said substrate has Euler angles of approximately (0°, 125° 137°, 0° \pm 5°), and said normalized film thickness H/ λ is within the range of approximately 0.003 to 0.05.
- 7. (issued) A surface acoustic wave device according to claim 1, wherein said interdigital transducer includes Ni as a major component, said substrate has Euler angles of approximately (0°, 125° 133°, 0° \pm 5°), and said normalized film thickness H/ λ is within the range of approximately 0.006 to 0.05.
- 8. (issued) A surface acoustic wave device according to claim 1, wherein said interdigital transducer includes Cr as a major component, said substrate has Euler angles of approximately (0°, 125° 147°, 0° \pm 5°), and said normalized film thickness H/ λ is within the range of approximately 0.003 to 0.05.
- 9. (issued) A surface acoustic wave device according to claim 1, wherein said interdigital transducer includes Zn as a major component, said substrate has Euler angles of approximately (0°, 125° 138°, 0° \pm 5°), and said normalized film thickness H/ λ is within the range of approximately 0.003 to 0.05.
- 10. (issued) A surface acoustic wave device according to claim 1, wherein said interdigital transducer includes W as a major component, said substrate has Euler angles of approximately (0°, 125° 138°, 0° \pm 5°), and said normalized film thickness H/ λ is within the range of approximately 0.002 to 0.05.

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- 11. (issued) A communication device including the surface acoustic wave device according to claim 1.
- 12. (issued) A communication device including the surface acoustic wave device according to claim 2.
- 13. (issued) A communication device including the surface acoustic wave device according to claim 3.
- 14. (issued) A communication device including the surface acoustic wave device according to claim 4.
- 15. (issued) A communication device including the surface acoustic wave device according to claim 5.
- 16. (issued) A communication device including the surface acoustic wave device according to claim 6.
- 17. (issued) A communication device including the surface acoustic wave device according to claim 7.
- 18. (issued) A communication device including the surface acoustic wave device according to claim 8.
- 19. (issued) A communication device including the surface acoustic wave device according to claim 9.
- 20. (issued) A communication device including the surface acoustic wave device according to claim 10.

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21. (new) A surface acoustic wave device comprising:

a LiTaO3 substrate; and

an interdigital transducer provided on the LiTaO3 substrate, said interdigital transducer containing as a major component at least one of Au, Ag, Ta, Mo, Cu, Ni, Cr, Zn, and W; wherein

said interdigital transducer has a normalized film thickness H/λ within a range of approximately 0.001 to approximately 0.05;

the substrate has Euler angles of approximately (0°, 136° to 147°, 0°±5°).

- . 22. (canceled).
- 23. (new) A surface acoustic wave device according to claim 21, wherein the substrate has Euler angles of approximately (0°, 136° to 137°, 0°±5°).
- 24. (new) A surface acoustic wave device according to claim 21, wherein the substrate has Euler angles of approximately (0°, 136.5°, 0°±5°).
- 25. (new) A surface acoustic wave device according to claim 21, wherein the normalized thickness H/λ is within a range of approximately 0.03 to approximately 0.05.
- 26. (new) A surface acoustic wave device according to claim 21, wherein the normalized thickness H/λ is approximately 0.04.
- 27. (new) A surface acoustic wave device according to claim 21, wherein the major component is Cu;

the normalized thickness H/λ is within a range of approximately 0.03 to approximately 0.05; and

the substrate has Euler angles of approximately (0°, 136° to 137°, 0°±5°).

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28. (new) A surface acoustic wave device according to claim 21, wherein the major component is Cu;

the normalized thickness H/λ is approximately 0.04; and the substrate has Euler angles of approximately (0°, 136° to 137°, 0°±5°).

29. (new) A surface acoustic wave device according to claim 21, wherein the major component is Cu;

the normalized thickness H/λ is within a range of approximately 0.03 to approximately 0.05; and

the substrate has Euler angles of approximately (0°, 136.5°, 0°±5°).

30. (new) A surface acoustic wave device according to claim 21, wherein the major component is Cu;

the normalized thickness H/λ is approximately 0.04; and the substrate has Euler angles of approximately (0°, 136.5°, 0°±5°).

31. (new) A surface acoustic wave device according to claim 21, wherein the major component is Cu; and

the substrate has Euler angles of approximately (0°, 136° to 137°, 0°±5°).

32. (new) A surface acoustic wave device according to claim 21, wherein the major component is Cu; and

the substrate has Euler angles of approximately (0°, 136.5°, 0°±5°).